

ABSTRACT

Dislocation of processing liquid pouring nozzles is prevented, smooth carrying of the processing liquid pouring nozzles is achieved, and the positional accuracy of the processing liquid pouring nozzles, processing accuracy and yield are improved. A substrate processing apparatus includes a spin chuck (50) for holding and rotating a wafer (W), a plurality of processing liquid pouring nozzles (60) for pouring processing liquids on a surface of the wafer (W), a solvent bath (70) for holding the processing liquid pouring nozzles at their home positions, and a nozzle-carrying arm (80) for detachably gripping desired one of the processing liquid pouring nozzles (60) held on the solvent bath (70) and carrying the desired processing liquid pouring nozzle (60) to a working position above the wafer (W). The processing liquid pouring nozzles (60) are held in alignment with straight lines (L) extending between the center (C) of the spin chuck (50) about which the spin chuck (50) rotates and nozzle holding openings (71) formed at suitable intervals in the solvent bath (70), respectively, and flexible supply tubes (61) connecting the processing liquid pouring nozzles (60) to processing liquid sources are arranged on extensions of the straight lines (L), respectively.

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